

L33-微縮光阻處理系統 (TRACK ACT8Z)

考核項目清單 | Bilingual Assessment Checklist

日期 Date : 2026/09/30

項次 No.	中文考核項目	English Assessment Item
1	機台狀況檢查與一般異常處理	Equipment Status Check and General Alarm Handling
	☐ 機台狀態檢查：狀態告示牌、操作畫面警示訊息查看	☐ Check equipment status: status signboard and warning messages on the operation screen.
	☐ 一般警示訊號處理。	☐ Handle general warning signals.
	☐ 不可自行排除之警示訊號處理方式：通知負責工程師及更換狀態告示牌。	☐ For warning signals that cannot be cleared independently: notify the responsible engineer and change the status signboard.
2	設備危害認知及危機處理	Equipment Hazard Awareness and Emergency Response
	☐ 設備危害認知。	☐ Understand equipment hazards.
	☐ 手臂搬送停止按鍵位置及使用時機。	☐ Know the location of the arm transfer stop button and when to use it.
	☐ EMO 位置及使用時機。	☐ Know the location of the EMO button and when to use it.
3	Chemical Box 與化學品的認識 (化學品接觸人員考核項目)	Chemical Box and Chemical Awareness (Assessment Items for Chemical-Handling Personnel)
	☐ 單元名稱/內容物：chemical box、resist、developer、solvent、HMDS、drain tank。	☐ Unit names / contents: chemical box, resist, developer, solvent, HMDS, and drain tank.
	☐ 安全資料表 (SDS) 的意義及放置位置。	☐ Understand the meaning of the Safety Data Sheet (SDS) and where it is stored.
	☐ 沖身洗眼器位置及使用方式。	☐ Know the location and proper use of the safety shower and eyewash station.
	☐ 狀態判斷：normal、abnormal。	☐ Determine status: normal or abnormal.
	☐ 顯影液主名稱及危害：2.38%TMAH，見 AD-10 SDS。	☐ Main developer name and hazards: 2.38% TMAH; refer to AD-10 SDS.
4	晶圓操作與晶舟取放	Wafer Handling and Carrier Loading / Unloading
	☐ 晶圓 (片) 拾取與乘載晶圓放置操作。	☐ Pick up wafers and place wafers into the carrier properly.

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	☐ 晶圓 (片) 檢查：斜插、疊片、正反面錯置、破損、晶背髒污、薄膜剝落、非標準尺寸規格。	☐ Inspect wafers for tilted insertion, double stacking, front/back side misorientation, breakage, backside contamination, film peeling, and non-standard size/specification.
	☐ 晶舟取放時機及放置檢查。	☐ Know when to load/unload the carrier and how to verify proper placement.
	☐ carrier stage 介面說明與操作。	☐ Understand and operate the carrier stage interface.
5	製程參數檢查、設定與機台操作	Process Parameter Check, Setup, and Equipment Operation
	☐ 操作畫面解說。	☐ Understand the operation screen.
	☐ 程式選擇與 RUN 貨。	☐ Select the recipe/program and run the lot.
	☐ 製程如何終止。	☐ Know how to terminate the process.
	☐ 機台使用完畢後續 Transfer 動作。	☐ Perform the required transfer actions after equipment use is completed.
6	設備簡介與製程觀念說明	Equipment Overview and Process Concept Explanation
	☐ 製程單元位置及功用：carrier station (carrier stage 、cassette 、wafer sensor 、CS Arm 、control panel 、EMO) 、main station (TRS 、TCP 、ADH 、LHP 、PHP 、HHP 、HCP 、COT 、DEV 、PS Arm) 。	☐ Locations and functions of process units: carrier station (carrier stage, cassette, wafer sensor, CS Arm, control panel, EMO) and main station (TRS, TCP, ADH, LHP, PHP, HHP, HCP, COT, DEV, PS Arm).
	☐ 塗佈及顯影製程流程及目的說明：ADH-HCP-COT-LHP 、PHP-HCP-DEV-HHP 。	☐ Explain the coating and development process flow and purpose: ADH-HCP-COT-LHP and PHP-HCP-DEV-HHP.
7	逾 30 分鐘未完成考試扣 25 分	If the assessment is not completed within 30 minutes, 25 points will be deducted.